

H5N2802PF

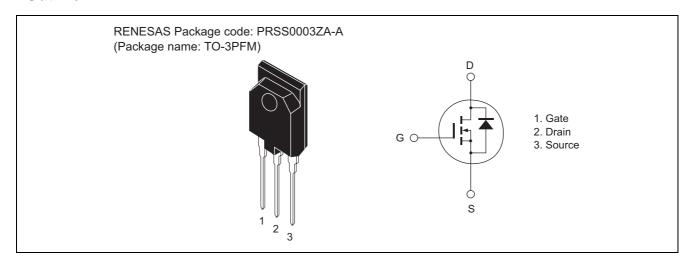
Silicon N Channel MOS FET High Speed Power Switching

REJ03G1298-0100 Rev.1.00 Oct.05.2005

Features

- Low on-resistance
- Low leakage current
- www.DataSheet U. High speed switching

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	280	V	
Gate to source voltage	V _{GSS}	±30	V	
Drain current	I _D	25	А	
Drain peak current	I _{D (pulse)} Note1	100	А	
Body-drain diode reverse drain current	I _{DR}	25	А	
Body-drain diode reverse drain peak current	I _{DR} (pulse)	100	А	
Avalanche current	I _{AP} Note3	13	А	
Avalanche energy	E _{AR} Note3	10.2	mJ	
Channel dissipation	Pch Note2	60	W	
Channel to case thermal impedance	θch-c	2.08	°C/W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

- 2. Value at Tc = 25°C
- 3. STch = 25° C, Tch $\leq 150^{\circ}$ C

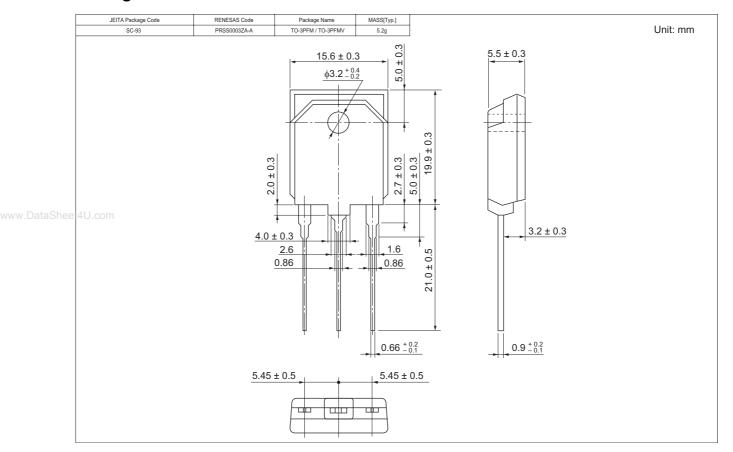
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	280	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	1	μΑ	$V_{DS} = 280 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	3.0	_	4.0	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward transfer admittance	y _{fs}	15	27		S	$I_D = 12.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note4}}$
Static drain to source on state	R _{DS(on)}	_	0.057	0.066	Ω	$I_D = 12.5 \text{ A}, V_{GS} = 10 \text{ V}^{Note4}$
resistance						
Input capacitance	Ciss	_	3600	_	pF	$V_{DS} = 25 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	450		pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	32	_	pF	
Turn-on delay time	t _{d(on)}	_	50	_	ns	$I_D = 12.5 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	_	90	_	ns	$R_L = 11.2 \Omega$, $Rg = 10 \Omega$
Turn-off delay time	$t_{d(off)}$	_	120	_	ns	
Fall time	t _f	_	75	_	ns	
Total gate charge	Qg	_	72	_	nC	$V_{DD} = 220 \text{ V}, V_{GS} = 10 \text{ V},$
Gate to source charge	Qgs	_	18	_	nC	$I_D = 25 A$
Gate to drain charge	Qgd	_	24	_	nC	
Body-drain diode forward voltage	V_{DF}	_	0.88	1.40	V	$I_F = 25 \text{ A}, V_{GS} = 0^{\text{Note4}}$
Body-drain diode reverse recovery time	t _{rr}	_	200	_	ns	$I_F = 25 \text{ A}, V_{GS} = 0,$
Body-drain diode reverse recovery charge	Q _{rr}	_	1.4	_	μС	di _F /dt = 100 A/μs

Notes: 4. Pulse test

Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
H5N2802PF-E	30 pcs	Plastic magazine

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